

Resin sealing method for a semiconductor device**Publication number:** US6261501**Publication date:** 2001-07-17**Inventor:** MIYAGAWA TSUTOMU (JP); AOKI KUNIHIRO (JP); KODAMA MASAHIRO (JP); MIYAJIMA FUMIO (JP)**Applicant:** APIC YAMADA CORP (US)**Classification:****- International:** **B29C33/68; B29C45/02; B29C45/14; H01L21/56; H01L21/60; B29L31/34; B29C33/56; B29C45/02; B29C45/14; H01L21/02;** (IPC1-7): B29C45/02; B29C70/74**- European:** B29C45/14M3; H01L21/56F; H01L21/56M4**Application number:** US19990235403 19990122**Priority number(s):** JP19980011382 19980123; JP19980345318 19981204**Also published as:**

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A resin sealing method for sealing a joining portion between a semiconductor chip 12 and a substrate 10 by filling a underfilled portion of a molded piece 40 in which a semiconductor chip is mounted on a substrate with solder bumps studded therebetween with sealing resin 14 by a transfer molding process, the method being characterized in that when the molded piece 40 is clamped with a mold of a transfer molding machine, the perimeter of the underfilled portion, except the end of a gate continuous to the underfilled portion, is closed with a release film 20, and in a state that the perimeter of the underfilled portion is closed, the sealing resin 14 having been supplied to a pot 42 provided in the mold is fed under pressure to the underfilled portion, to thereby fill the underfilled portion.

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